Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040201087"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:15
S2	1	'samsung' and 'dong-ho lee'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:16
S3	85	lee-dong-ho.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:16
S4	16	lee-dong-ho.in. and 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:21
S5	2145	@ad<="20040102" and (257/678).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:22
S6	526	@ad<="20040102" and (257/685).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:24
S7	1654	@ad<="20040102" and (257/686).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:22
S8	835	@ad<="20040102" and (257/730).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:24
S9	3376	@ad<="20040102" and (257/777-778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:25
S10	957	@ad<="20040102" and (257/779).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:36

S11	1307	@ad<="20040102" and (257/693). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:27
S13	33	@ad<="20040102" and 'stack package' and 'chip scale package' and 'ball grid array'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:49
S14	2040	@ad<="20040102" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:29
S15	1	"6376769".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:29
S16	1	"6108210".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:30
S17	1	"5950304".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:30
S18	1	"6218731".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:31
S19	1	"5793870".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:32
S20	1	"5714405".PN.	USPAT; USOCR	OR	ON	2005/04/21 10:32
S22	45	@ad<="20040102" and 'chip stack' and 'chip scale package' and 'ball grid array'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S23	50	@ad<="20040102" and 'chip stack' and 'CSP' and 'BGA'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 10:50
S24	0	@ad<="20040102" and 'chip stack' and 'chip scale package' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S25	3	@ad<="20040102" and 'chip stack' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:20
S26	11	@ad<="20040102" and 'chip scale package' and 'connecting board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:34

S27	10	@ad<="20040102" and 'chip scale package' and 'coupled' and 'flexible circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:42
S28	14	@ad<="20040102" and 'CSP' and 'coupled' and 'flexible circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:35
S29	672	@ad<="20040102" and (257/727). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:36
S30	643	@ad<="20040102" and 'chip scale package' and 'stack'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:42
S31	46	@ad<="20040102" and 'chip scale package' and 'connect' same 'flexible' with 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:55
S32	1	"6376769".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:45
S33	1	"6218731".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:46
S34	1	"5793870".PN.	USPAT; USOCR	OR	ON	2005/04/21 13:46
S35	5	Cha-Ki-Bon.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:55